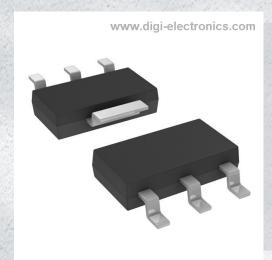


# **SBCP56T1G Datasheet**



https://www.DiGi-Electronics.com

DiGi Electronics Part Number SBCP56T1G-DG

Manufacturer onsemi

Manufacturer Product Number SBCP56T1G

Description TRANS NPN 80V 1A SOT223

Detailed Description Bipolar (BJT) Transistor NPN 80 V 1 A 130MHz 1.5 W

Surface Mount SOT-223 (TO-261)



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

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# **Purchase and inquiry**

Manufacturer Product Number:	Manufacturer:
SBCP56T1G	onsemi
Series:	Product Status:
	Active
Transistor Type:	Current - Collector (Ic) (Max):
NPN	1 A
Voltage - Collector Emitter Breakdown (Max):	Vce Saturation (Max) @ lb, lc:
80 V	500mV @ 50mA, 500mA
Current - Collector Cutoff (Max):	DC Current Gain (hFE) (Min) @ Ic, Vce:
100nA (ICBO)	40 @ 150mA, 2V
Power - Max:	Frequency - Transition:
1.5 W	130MHz
Operating Temperature:	Grade:
-65°C ~ 150°C (TJ)	Automotive
Qualification:	Mounting Type:
AEC-Q101	Surface Mount
Package / Case:	Supplier Device Package:
TO-261-4, TO-261AA	SOT-223 (TO-261)
Base Product Number:	
SBCP56	

# **Environmental & Export classification**

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	

8541.29.0075



# NPN Silicon Epitaxial Transistor

## **BCP56 Series**

These NPN Silicon Epitaxial transistors are designed for use in audio amplifier applications. The device is housed in the SOT-223 package, which is designed for medium power surface mount applications.

#### **Features**

- High Current: 1.0 A
- The SOT-223 package can be soldered using wave or reflow. The formed leads absorb thermal stress during soldering, eliminating the possibility of damage to the die
- Available in 12 mm Tape and Reel
   Use BCP56T1G to Order the 7 inch/1000 Unit Reel
   Use BCP56T3G to Order the 13 inch/4000 Unit Reel
- PNP Complement is BCP53T1G
- S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### MAXIMUM RATINGS (T<sub>C</sub> = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	80	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	100	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	5	Vdc
Collector Current	Ic	1	Adc
Collector Current - Peak (Note 1)	I <sub>CM</sub>	2	Adc
Total Power Dissipation @ T <sub>A</sub> = 25°C (Note 2) Derate above 25°C	P <sub>D</sub>	1.5 12	W mW/°C
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to 150	°C

#### THERMAL CHARACTERISTICS

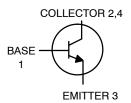
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient (surface mounted)	$R_{ heta JA}$	83.3	°C/W
Maximum Temperature for Soldering Purposes Time in Solder Bath	TL	260 10	°C Sec

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1

- 1. Reference SOA curve.
- 2. Device mounted on a FR-4 glass epoxy printed circuit board 1.575 in x 1.575 in x 0.0625 in; mounting pad for the collector lead = 0.93 sq in.

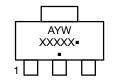
## MEDIUM POWER NPN SILICON HIGH CURRENT TRANSISTOR SURFACE MOUNT





SOT-223 CASE 318E STYLE 1

#### **MARKING DIAGRAM**



XXXXX = Specific Device Code A = Assembly Location

Y = Year W = Work Week • Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering, marking and shipping information on page 5 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 5.

### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Min	Тур	Max	Unit
•	-	•	-	
V <sub>(BR)CBO</sub>	100	_	_	Vdc
V <sub>(BR)CEO</sub>	80	-	-	Vdc
V <sub>(BR)EBO</sub>	5.0	_	_	Vdc
I <sub>CBO</sub>	-	-	100	nAdc
I <sub>EBO</sub>	-	-	10	μAdc
	25 40 63 100 25	- - -	- 250 160 250	-
V <sub>CE(sat)</sub>	-	_	0.5	Vdc
V <sub>BE(on)</sub>	-	_	1.0	Vdc
•	•	•	•	
t <sub>r</sub>	-	14	-	ns
t <sub>d</sub>	-	9	-	ns
t <sub>s</sub>	-	714	-	ns
t <sub>f</sub>	-	58	-	ns
		_		
f <sub>T</sub>	-	130	_	MHz
	V(BR)CBO V(BR)CEO V(BR)EBO ICBO IEBO VCE(sat) VBE(on) tr td td ts	V(BR)CBO 100  V(BR)CEO 80  V(BR)EBO 5.0  ICBO -  IEBO -  hFE 25 40 63 100 25  VCE(sat) -  VBE(on) -  t <sub>r</sub> -  t <sub>d</sub> -  t <sub>f</sub> -	V(BR)CBO 100 -  V(BR)CEO 80 -  V(BR)EBO 5.0 -  ICBO  IEBO  NCE(sat)  VBE(on)  t <sub>f</sub> - 14  t <sub>d</sub> - 9  t <sub>s</sub> - 714  t <sub>f</sub> - 58	V(BR)CBO       100       -       -         V(BR)CEO       80       -       -         V(BR)EBO       5.0       -       -         ICBO       -       -       100         IEBO       -       -       10         hFE       25

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width ≤ 300 µs, Duty Cycle ≤ 2.0%

#### TYPICAL ELECTRICAL CHARACTERISTICS

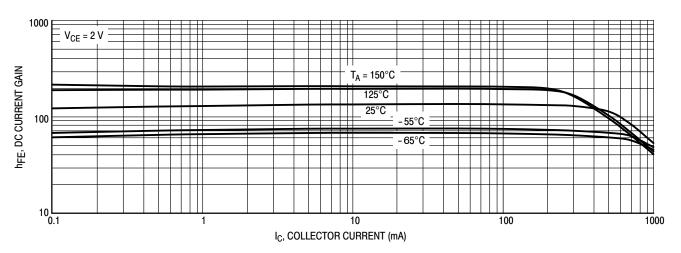


Figure 1. DC Current Gain

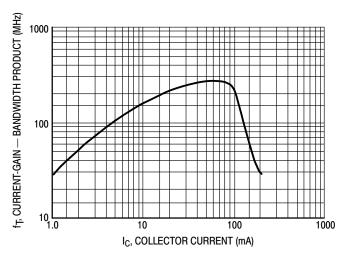


Figure 2. Current-Gain - Bandwidth Product

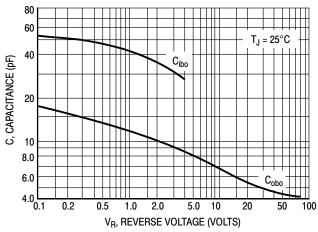


Figure 3. Capacitance

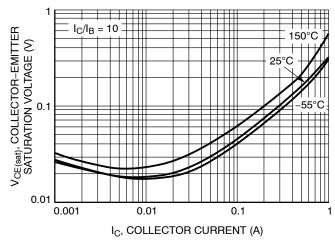


Figure 4. Collector Emitter Saturation Voltage vs. Collector Current

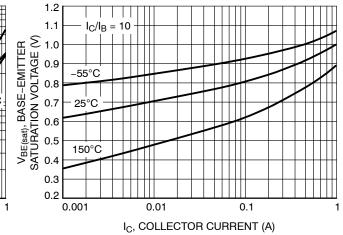


Figure 5. Base Emitter Saturation Voltage vs.
Collector Current

#### TYPICAL ELECTRICAL CHARACTERISTICS

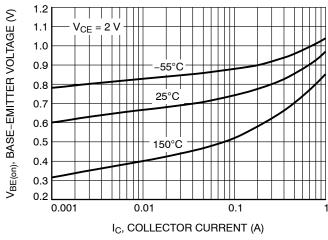


Figure 6. Base Emitter Voltage vs. Collector Current

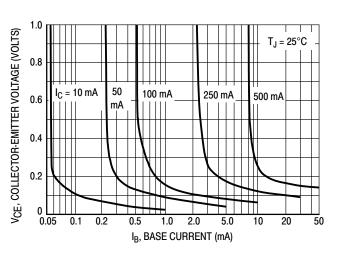
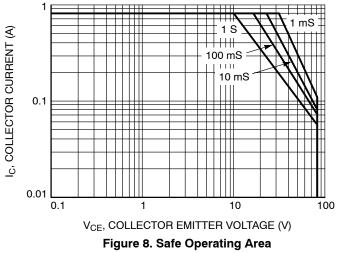


Figure 7. Collector Saturation Region



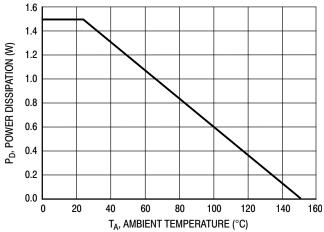


Figure 9. Power Derating Curve

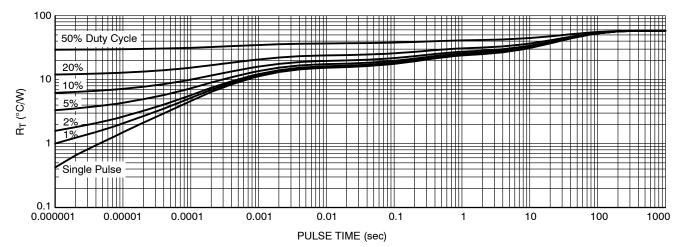


Figure 10. Thermal Response

#### **ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>	
BCP56T1G	ВН	SOT-223		1000 / Tape & Reel
SBCP56T1G*		(Pb-Free)		
BCP56T3G	ВН	SOT-223	4000 / Tape & Reel	
SBCP56T3G*		(Pb-Free)		
BCP56-10T1G	BH-10	SOT-223	1000 / Tape & Reel	
SBCP56-10T1G*		(Pb-Free)		
NSVBCP56-10T3G*	BH-10	SOT-223 (Pb-Free)	4000 / Tape & Reel	
BCP56-16T1G	BH-16	SOT-223	1000 / Tape & Reel	
SBCP56-16T1G*		(Pb-Free)		
BCP56-16T3G	BH-16	SOT-223	4000 / Tape & Reel	
SBCP56-16T3G*		(Pb-Free)		

#### **DISCONTINUED** (Note 4)

BCP56-10T3G	BH-10	SOT-223 (Pb-Free)	4000 / Tape & Reel
l .			

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

<sup>4.</sup> **DISCONTINUED:** This device is not recommended for new design. Please contact your **onsemi** representative for information. The most current information on this device may be available on <a href="https://www.onsemi.com">www.onsemi.com</a>.

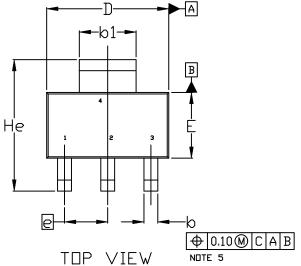


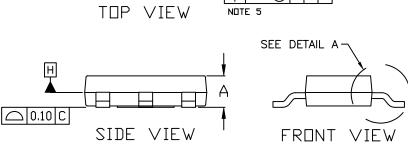
## **MECHANICAL CASE OUTLINE**

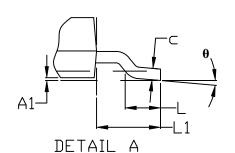
PACKAGE DIMENSIONS



**DATE 02 OCT 2018** 



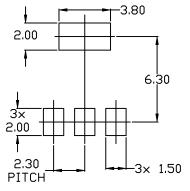




#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSIONS D & E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.200MM PER SIDE.
- 4. DATUMS A AND B ARE DETERMINED AT DATUM H.
- A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
- POSITIONAL TOLERANCE APPLIES TO DIMENSIONS to AND tol.

	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α	1.50	1.63	1.75	
A1	0.02	0.06	0.10	
b	0.60	0.75	0.89	
b1	2.90	3.06	3.20	
C	0.24	0.29	0.35	
D	6.30	6.50	6.70	
E	3.30	3.50	3.70	
е	i	5'30 B2C	;	
L	0.20			
L1	1.50	1.75	2.00	
He	6.70	7.00	7.30	
θ	0°		10°	



RECOMMENDED MOUNTING **FOOTPRINT** 

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DESCRIPTION:	SOT-223 (TO-261)		PAGE 1 OF 2

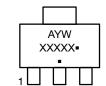
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#### **SOT-223 (TO-261)** CASE 318E-04 ISSUE R

**DATE 02 OCT 2018** 

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. ANODE 2. CATHODE 3. NC 4. CATHODE	STYLE 3: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 4: PIN 1. SOURCE 2. DRAIN 3. GATE 4. DRAIN	STYLE 5: PIN 1. DRAIN 2. GATE 3. SOURCE 4. GATE
STYLE 6: PIN 1. RETURN 2. INPUT 3. OUTPUT 4. INPUT	STYLE 7: PIN 1. ANODE 1 2. CATHODE 3. ANODE 2 4. CATHODE	STYLE 8: CANCELLED	STYLE 9: PIN 1. INPUT 2. GROUND 3. LOGIC 4. GROUND	STYLE 10: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE
STYLE 11: PIN 1. MT 1 2. MT 2 3. GATE 4. MT 2	STYLE 12: PIN 1. INPUT 2. OUTPUT 3. NC 4. OUTPUT	STYLE 13: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR		

# GENERIC MARKING DIAGRAM\*



A = Assembly Location

Y = Year W = Work Week

XXXXX = Specific Device Code • Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	SOT-223 (TO-261)		PAGE 2 OF 2

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